DFCT45G67NDWAA-RB2

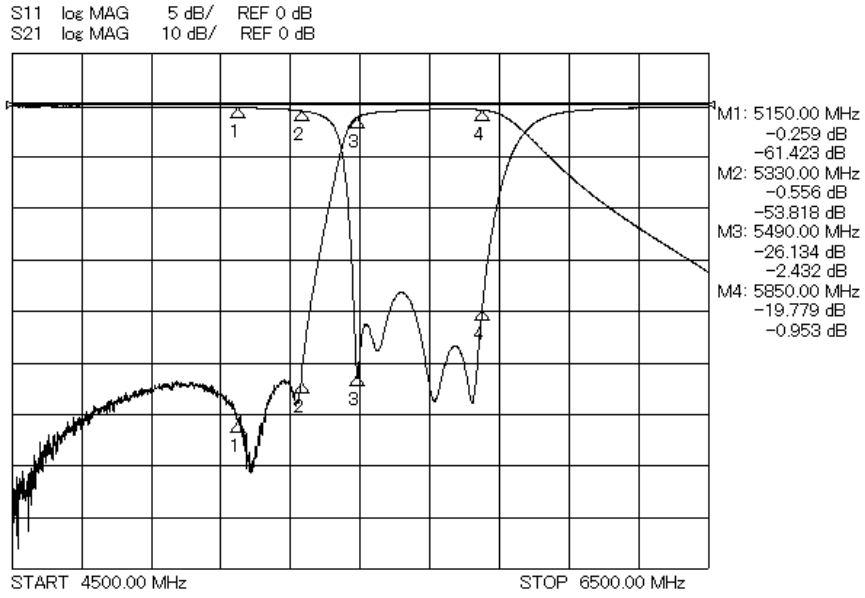
Part Number/Tape & Reel information

Part Number	Packaging	MOQ
DFCT45G67NDWAA-RB2	330 mm dia. reel	2000 pcs/reel

Specifications -35 to +85°C

Parameter	IN to OUT
Center Frequency	F0 : 5670 MHz
Band Width (BW)	F0 +/- 180 MHz
Insertion Loss at BW	3.0 dB max.
Ripple at BW	2.2 dB max.
V.S.W.R. at BW	1.9 max.
Input Power	1.0 W max.
Attenuation	30 ~ 2700 MHz 38dB min. 3453 ~ 3547 MHz 38dB min. 3667 ~ 3883 MHz 33dB min. 5150 ~ 5330 MHz 50dB min. 7200 ~ 7500 MHz 20dB min.
Characteristic Impedance	50 Ohms

Frequency Response



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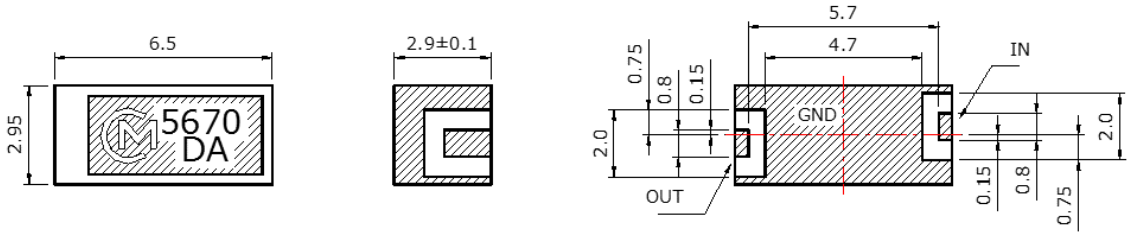
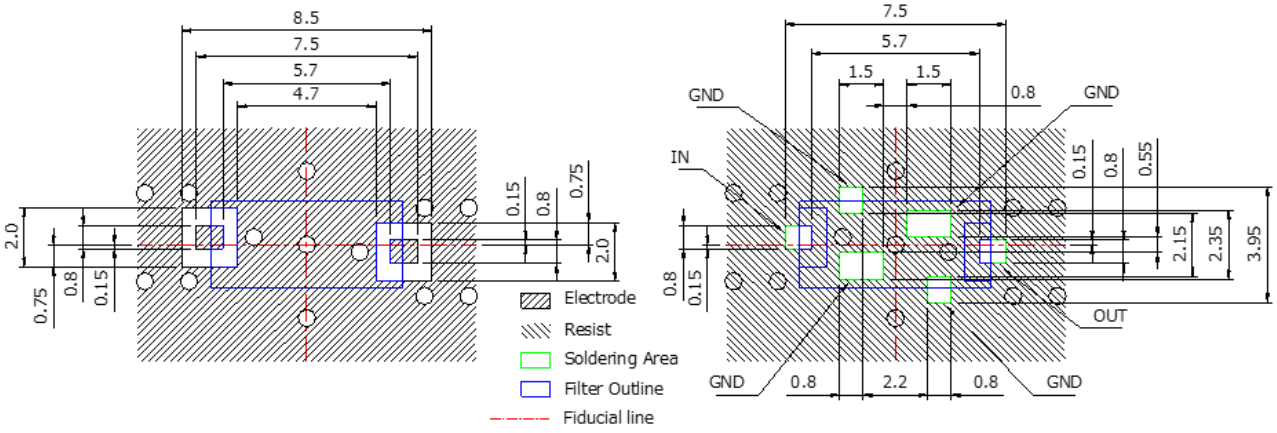
Dimensions and Marking

TOP VIEW SIDE VIEW BOTTOM VIEW



Tolerance : +/-0.3mm
Unit : mm

Recommend Land Pattern (reference)



Unit : mm

Electrode Solder Resist

Note : Impedance of signal lines should be 50 ohms including land pattern. This standard condition is applying to the BT resin board (t = 0.4, dielectric constant = 3.6, copper plating on both surfaces).

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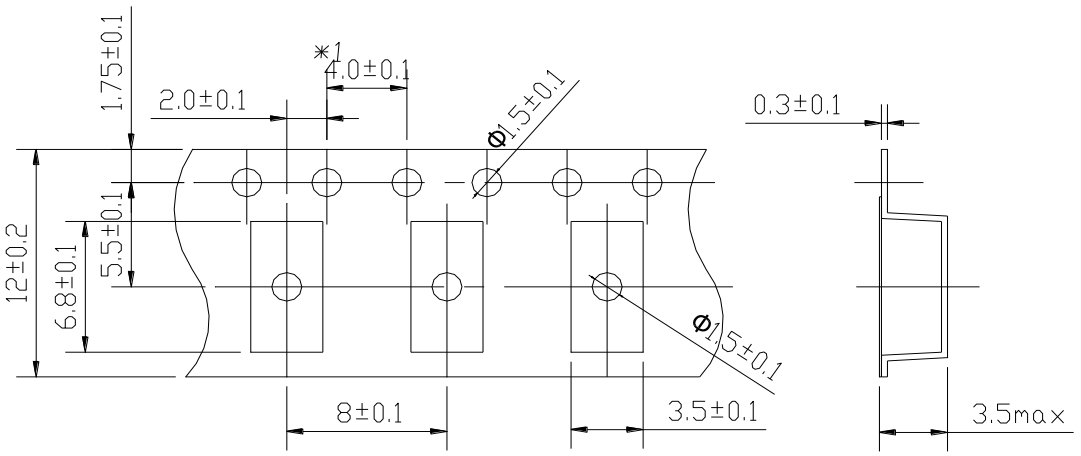
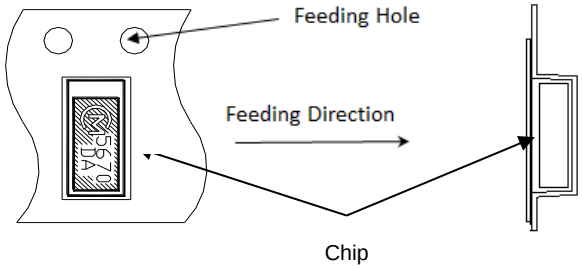
Dimensions of Carrier Tape

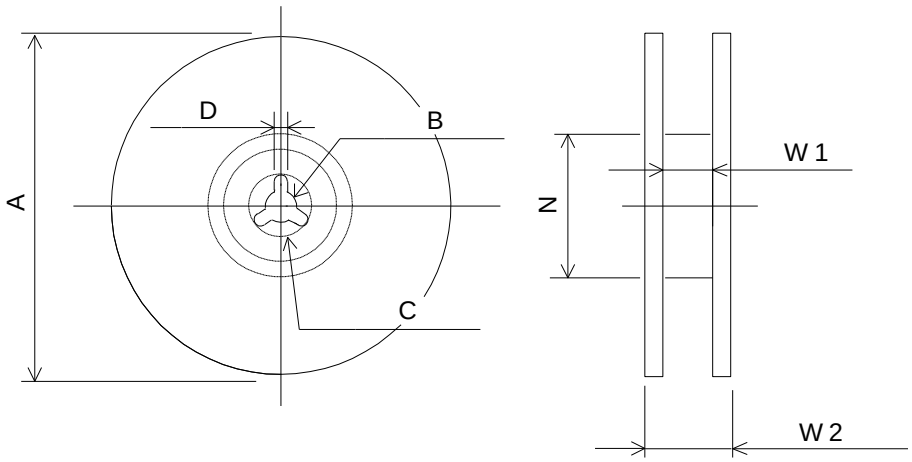
∗1 Cumulative tolerance of max. ± 0.3 every 10 pitches





DIMENSIONS : mm

Dimensions of Reel



Murata Part Number	A+/-2.0	B+/-0.5	C+/-0.8	D+/-0.5	N (min.)	W1+/-1.5	W2 (max.)
DFCT45G67NDWAA-RB2	330	dia 13	dia 21	2.4	50	12.5	23

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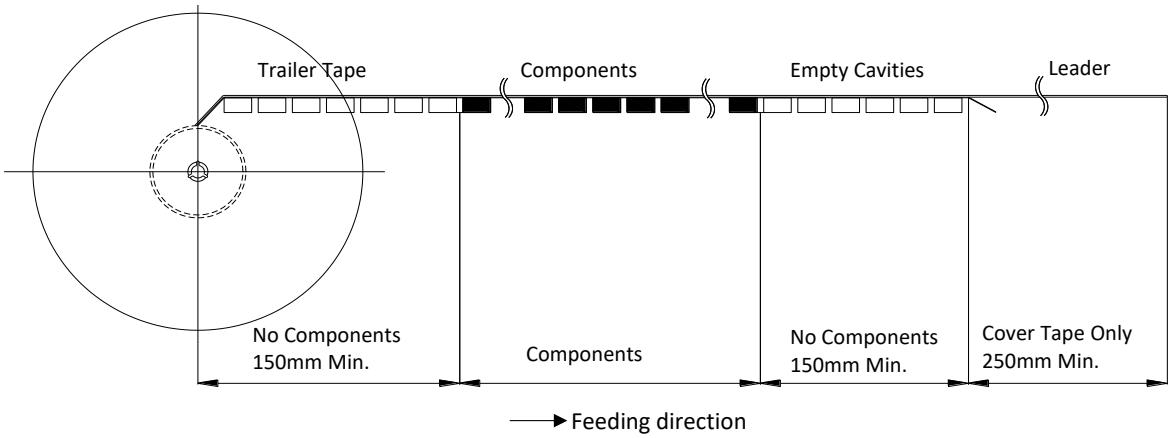
Taping Condition



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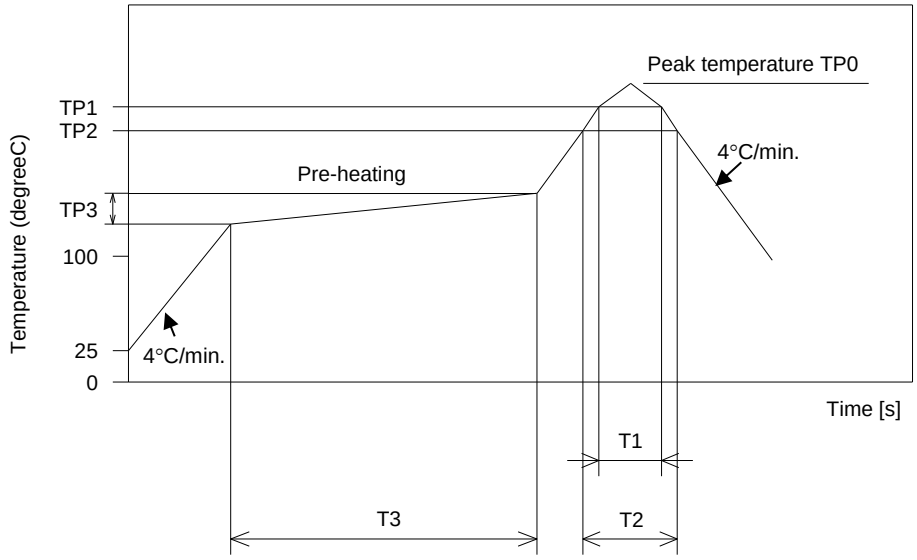
Reflow Soldering Standard Conditions



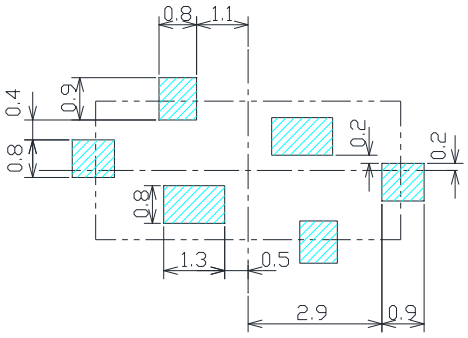
Measuring point of temperature : IN-OUT Terminals of The Device

Reflow Soldering : Both Convection and Infrared Rays, Hot Air and Hot Plate

		TP0 (°C)	TP1 (°C)	T1 (s)	TP2 (°C)	T2 (s)	TP3 (°C)	T3 (s)
Reflow standard condition	Sn-3Ag-0.5Cu solder	255+/-5	250	10 max.	220	20 to 40	150 to 190	60 to 120
Test condition of reflow heat resistance		255+/-5	250	10 max.	220	20 to 40	150 to 190	60 to 120

Reflow soldering is available 2 times for above test condition of reflow heat resistance.

Soldering Mask Pattern



Unit : mm

Note : The thickness of soldering mask is 0.1mm.